



## Material Content Data Sheet



<b>Sales Product Name</b>		BFP 780 H6327		<b>Issued</b>		8. May 2015		
<b>MA#</b>		MA001151148						
<b>Package</b>		PG-SOT343-4-2		<b>Weight*</b>		6.94 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.03		259	
	noble metal	gold	7440-57-5	0.007	0.10		1005	
	inorganic material	silicon	7440-21-3	0.052	0.74	0.87	7449	8713
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		99	
	non noble metal	titanium	7440-32-6	0.003	0.05		497	
	non noble metal	chromium	7440-47-3	0.010	0.15		1491	
	non noble metal	copper	7440-50-8	3.433	49.48	49.69	494768	496855
wire	noble metal	gold	7440-57-5	0.010	0.15	0.15	1486	1486
encapsulation	organic material	carbon black	1333-86-4	0.030	0.43		4331	
	plastics	epoxy resin	-	0.646	9.31		93109	
	inorganic material	silicondioxide	60676-86-0	2.329	33.56	43.30	335627	433067
leadfinish	non noble metal	tin	7440-31-5	0.199	2.87	2.87	28712	28712
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31167	31167
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

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